

PCN Number:	20240314002.1	PCN Date:	March 14, 2024
Title:	Datasheet for UCC21759-Q1		
Customer Contact:	Change Management	Dept:	Quality Services
Proposed 1st Ship Date:	Sept. 14, 2024		
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.



UCC21759-Q1

SLUSEB4B – AUGUST 2020 – REVISED FEBRUARY 2024

Changes from Revision A (December 2020) to Revision B (February 2024)	Page
• Added Automotive to title.....	1
• Added sub-bullets under AEC-Q100 qualifications.....	1
• Changed safety-related certifications in Features, changed isolation rating according to the latest standard...	1
• Changed isolation voltage based on latest standard.....	1
• Added what to do with unused pins to Pin Functions Table.....	3
• Changed recommended value of decoupling capacitors.....	3
• Added recommended decoupling capacitor layout placement.....	3
• Changed VDE ratings per the latest standard.....	6
• Changed certification table according to latest standard and status.....	7
• Deleted short circuit clamping max condition.....	8
• Changed V _{Ain} lower limit to 0.6V.....	8
• Changed V _{CLMPT} -VDD test condition current direction.....	8
• Changed I _{CHG} lower limit to 430μA.....	8
• Added soft turn-off test condition.....	8
• Changed isolation voltage based on latest standard.....	24
• Changed DESAT protection figure.....	29
• Changed soft turn-off figure.....	29
• Added function state showing gate driver turning on. Changed RDY condition when VCC is PD.	32
• Changed isolation voltage based on latest standard.....	33
• Changed Current Buffer for Increased Drive Strength figure.....	44

The datasheet number will be changing.

Device Family	Change From:	Change To:
UCC21759-Q1	SLUSEB4A	SLUSEB4B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/UCC21759-Q1>

Reason for Change:

This particular PCN is related to TI's multiyear transition plan for our two remaining factories with 150-millimeter production (DFAB in Dallas, Texas, and SFAB in Sherman, Texas). DFAB will remain open, but will focus on 200-mm production, with a smaller set of technologies. SFAB will close no earlier than 2024 and no later than 2025. As referenced in the "reason for change" below, these changes are part of our multiyear plan to transition these products to newer, more efficient manufacturing processes and technologies, underscoring our commitment to product longevity and supply continuity.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Electrical specification performance changes as indicated above.

Changes to product identification resulting from this PCN:

None.

Product Affected:

UCC21759QDWQ1

UCC21759QDWRQ1

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.